



TE Internal #: 2013289-2
 SO DIMM Sockets, Double Data Rate (DDR) 3, Stack Height .205 in [5.2 mm], Right Angle Module Orientation, Surface Mount Mount, Cable-to-Board

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 3**
 Stack Height: **5.2 mm [.205 in]**
 Module Orientation: **Right Angle**
 PCB Mounting Style: **Surface Mount**
 Connector System: **Cable-to-Board**

Features

Product Type Features

DRAM Type	Double Data Rate (DDR) 3
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket

Configuration Features

Number of Bays	2
Center Key	Offset Left
Number of Keys	1
Module Orientation	Right Angle
Number of Positions	204
Number of Rows	2
Keying	Standard

Electrical Characteristics

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DRAM Voltage	1.5 V
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Signal Characteristics

SGRAM Voltage	1.5 V
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Body Features

Ejector Location	Both Ends
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Latch Material	Stainless Steel
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Latch Plating Material	Tin
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Module Key Type	SGRAM
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Ejector Type	Locking
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Connector Profile	Standard
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Contact Features

Socket Style	SO DIMM
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PCB Contact Termination Area Plating Material	Gold
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Contact Base Material	Copper Alloy
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Contact Mating Area Plating Material	Gold
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Contact Mating Area Plating Material Thickness	.254 μm [10 μin]
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Contact Current Rating (Max)	.5 A
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Socket Type	Memory Card
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Termination Features

Insertion Style	Cam-In
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Mechanical Attachment

PCB Mount Retention	With
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PCB Mount Retention Type	Solder Peg
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PCB Mounting Style	Surface Mount
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Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	.6 mm[.024 in]
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Housing Color	Black
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Housing Material	High Temperature Thermoplastic
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Dimensions

Stack Height	5.2 mm[.205 in]
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Row-to-Row Spacing	8.2 mm[.322 in]
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Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Semi-Hard Tray Assembly
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Packaging Quantity	20
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Other

Comment	With floating peg.
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2021 (211) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents

Product Drawings

[SEMI-HARD TRAY DDR3 204P 5.2H STD Au0.25](#)

English

CAD Files

Customer View Model

[ENG_CVM_CVM_2013289-2_B.2d_dxf.zip](#)

English

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2013289-2_B.3d_igs.zip](#)

English

Customer View Model



[ENG_CVM_CVM_2013289-2_B.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[DDR3 DIMM Sockets Flyer 6-1773454-7 05/09](#)

English

[6-1773457-3_DDR3_DIMM_SOCKETS](#)

Product Specifications

[Product Specification](#)

English

Product Environmental Compliance

[TE Material Declaration](#)

English